

Global Small Outline Integrated Circuit (SOIC) Package Market Growth 2026-2032

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Abstracts

The global Small Outline Integrated Circuit (SOIC) Package market size is predicted to grow from US\$ million in 2025 to US\$ million in 2032; it is expected to grow at a CAGR of %from 2026 to 2032.

A small outline integrated circuit (SOIC) is a surface-mounted integrated circuit (IC) package which occupies an area about 30?50% less than an equivalent dual in-line package (DIP), with a typical thickness being 70% less. They are generally available in the same pin-outs as their counterpart DIP ICs. The convention for naming the package is SOIC or SO followed by the number of pins.

The global Small Outline Integrated Circuit (SOIC) package market refers to the market for a type of surface mount integrated circuit (IC) package known as SOIC. SOIC packages are widely used in the electronics industry for their compact size, ease of manufacturing, and compatibility with automated assembly processes.

Here are some key factors driving the growth of the global SOIC package market:

Miniaturization and High-Density Packaging: As electronic devices continue to become smaller and more compact, there is a growing demand for IC packages that offer high-density integration. SOIC packages are known for their small outline and compact size, allowing for efficient use of space on printed circuit boards (PCBs) and enabling the miniaturization of devices.

Wide Application in Various Industries: SOIC packages are used in a wide range of industries, including consumer electronics, automotive, industrial, telecommunications, and healthcare. They are suitable for applications such as power management, signal

processing, microcontrollers, memory, and interface circuits. The broad applicability of SOIC packages contributes to their market growth.

Cost-Effectiveness and Manufacturing Efficiency: SOIC packages are cost-effective to manufacture compared to other types of IC packages, such as quad flat no-leads (QFN) or ball grid array (BGA). Additionally, their compatibility with automated assembly processes makes them highly efficient for high-volume production, reducing manufacturing costs and increasing productivity.

Thermal Performance and Reliability: SOIC packages have good thermal performance due to their exposed leads, which allows heat to be dissipated effectively. This feature is particularly important for power-related applications where heat dissipation is critical. Furthermore, SOIC packages offer good electrical performance and reliability, meeting the stringent requirements of various industries.

Compatibility with Legacy Systems: SOIC packages have been widely used for many years, and they have become a standard package type for many ICs. This compatibility with legacy systems makes them attractive for replacement or upgrade purposes, allowing for seamless integration into existing designs without major changes.

Advancements in Technology: The SOIC package market has benefited from advancements in semiconductor manufacturing technology. These advancements have led to the development of smaller pitch sizes, higher pin counts, and higher operating speeds for SOIC packages, expanding their capabilities and increasing their adoption in new applications.

Growing Demand for Portable and Wearable Devices: The increasing popularity of portable electronics, such as smartphones, tablets, wearables, and IoT devices, fuels the demand for compact and lightweight IC packages like SOIC. These devices require smaller and more energy-efficient components, driving the growth of the SOIC package market.

In conclusion, the global SOIC package market is driven by the need for miniaturization, high-density packaging, wide application in various industries, cost-effectiveness, manufacturing efficiency, thermal performance, compatibility with legacy systems, advancements in technology, and the demand for portable and wearable devices. As the electronics industry continues to evolve and demand for small, reliable, and high-performance IC packages increases, the market for SOIC packages is expected to grow significantly. The global Small Outline Integrated Circuit (SOIC) package market refers to

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LP Information, Inc. (LPI) ' newest research report, the "Small Outline Integrated Circuit (SOIC) Package Industry Forecast" looks at past sales and reviews total world Small Outline Integrated Circuit (SOIC) Package sales in 2025, providing a comprehensive analysis by region and market sector of projected Small Outline Integrated Circuit (SOIC) Package sales for 2026 through 2032. With Small Outline Integrated Circuit (SOIC) Package sales broken down by region, market sector and sub-sector, this report provides a detailed analysis in US\$ millions of the world Small Outline Integrated Circuit (SOIC) Package industry.

This Insight Report provides a comprehensive analysis of the global Small Outline Integrated Circuit (SOIC) Package landscape and highlights key trends related to product segmentation, company formation, revenue, and market share, latest development, and M&A activity. This report also analyzes the strategies of leading global companies with a focus on Small Outline Integrated Circuit (SOIC) Package portfolios and capabilities, market entry strategies, market positions, and geographic footprints, to better understand these firms' unique position in an accelerating global Small Outline Integrated Circuit (SOIC) Package market.

This Insight Report evaluates the key market trends, drivers, and affecting factors shaping the global outlook for Small Outline Integrated Circuit (SOIC) Package and breaks down the forecast by Type, by Application, geography, and market size to highlight emerging pockets of opportunity. With a transparent methodology based on hundreds of bottom-up qualitative and quantitative market inputs, this study forecast

offers a highly nuanced view of the current state and future trajectory in the global Small Outline Integrated Circuit (SOIC) Package.

This report presents a comprehensive overview, market shares, and growth opportunities of Small Outline Integrated Circuit (SOIC) Package market by product type, application, key manufacturers and key regions and countries.

Segmentation by Type:

Mini-SOIC

Small Outline J-Lead Package

Others

Segmentation by Application:

Industrial

Consumer Electronics

Automotive

Medical Devices

Military and Defense

This report also splits the market by region:

Americas

United States

Canada

Mexico

Brazil

APAC

China

Japan

Korea

Southeast Asia

India

Australia

Europe

Germany

France

UK

Italy

Russia

Middle East & Africa

Egypt

South Africa

Israel

Turkey

GCC Countries

The below companies that are profiled have been selected based on inputs gathered from primary experts and analysing the company's coverage, product portfolio, its market penetration.

3M

Enplas Corporation

Toshiba Electronic Devices and Storage Corporation

Intel Corporation

Loranger International Corporation

Komachine

Aries Electronics Inc

Johnstech International

Mill-Max Manufacturing Corporation

Molex

Foxconn

Sensata Technologies

Plastronics

TE Connectivity

Socionext America Inc

WinWay Technology Co

ChipMOS Technologies Inc

Yamaichi Electronics

Key Questions Addressed in this Report

What is the 10-year outlook for the global Small Outline Integrated Circuit (SOIC) Package market?

What factors are driving Small Outline Integrated Circuit (SOIC) Package market growth, globally and by region?

Which technologies are poised for the fastest growth by market and region?

How do Small Outline Integrated Circuit (SOIC) Package market opportunities vary by end market size?

How does Small Outline Integrated Circuit (SOIC) Package break out by Type, by Application?

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